



FOR IMMEDIATE RELEASE

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SHENMAO America Partners with Southwest Systems Technology, Inc.

SAN JOSE, CA — December 2018 — SHENMAO America, Inc. is pleased to announce the appointment of Southwest Systems Technology, Inc. as its representative in the states of Texas, Oklahoma, Arkansas and Louisiana. The company has offices in Texas and Mexico.

“We are honored to be working with one of the top three solder companies in the world,” stated Scott Fillebrown, Managing Director at Southwest Systems Technology. “SHENMAO’s wide range of products, combined with their competitive approach to business is a winning combination.”

Southwest Systems Technology specializes in the sales and support of capital equipment, benchtop tools and manufacturing consumables, and its sales engineers are trained in the latest industry processes and technologies. Founded in 1989, the company sells products in both the electronic and semiconductor manufacturing industries.

For more information about Southwest Systems Technology, contact Scott Fillebrown at Scott@SWSystems.com or visit www.swsystems.com.

SHENMAO has successfully been approved by many international well-known electronic manufacturers. The company strives to offer the best quality without compromising cost and time-to-market while providing maximum value to all customers. SHENMAO America, Inc. blends SMT solder paste at its facility in San Jose, CA for distribution in North America.

For more information, please visit www.shenmao.com.

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About SHENMAO

SHENMAO is dedicated to the production of solder products including Water Soluble and No-clean Solder Paste, Laser Solder Paste, Solder Preforms, Cored Solder Wire, Wave Solder Bar Alloys, Wave Soldering Fluxes, Extremely Pure Solder Powder up to Type 8, BGA and Micro BGA Solder Sphere, Wafer Level Packaging Solder Paste and Fluxes, LED Die Attach Paste, High Performance Liquid Fluxes, Solder Preform, Solar Ribbon, Plating Anode used in PCB Fabrication, Assembly and Semiconductor Packaging Processes.